

# Functional Test-Cost Reduction Based on Fault Tree Analysis and Binary Optimization

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**Abstract:** With the rapid increase in the complexity of electronics, the cost of the functional testing process used to ensure product functionality continues to rise. Optimization modeling based on reliability analysis is an effective approach to reduce testing costs. However, the reliability calculations of existing methods often exhibit significant deviations, making it challenging to guarantee the effectiveness of the resulting testing strategies in practical applications. To address this issue, this article proposes an optimization modeling method that integrates statistical analysis and reliability analysis. The expression for the reliability of the system's key stage is formulated by analyzing the system's reliability. Statistical analysis is utilized to exploit the inherent reliability information in the enormous process data to determine the probability of the root causes of system failures. The reliability of the key stage is quantitatively calculated based on the structure of the fault tree tailored for the system. On this basis, a binary optimization model is established to obtain a testing strategy with strong generalization ability and reduce the cost of functional testing. The effectiveness of the proposed method is verified through a simulation case study.

**Key Words:** Intelligent Manufacturing, Optimization Modeling, Fault Tree Analysis, Functional Testing, Cost Reduction

## 1 Introduction

Functional testing is a crucial process in electronics manufacturing for assessing product quality. With the rapid increase in the complexity of electronics, the cost of functional testing is rising, and its impact on the overall manufacturing cost cannot be ignored [1]. To reduce testing costs, production often divides the functional testing process into two stages: board-level functional testing and system-level functional testing. Board-level functional testing reduces rework costs by pre-testing some of the main functions of the motherboard. It usually determines the items to be tested or the percentage of the motherboard to be tested based on a specific strategy. On the other hand, system-level functional testing comprehensively tests all the functions of the finished product to maximize the shipping yield rate [2]. The key to reducing testing costs lies in designing the testing strategy for the board-level functional testing stage [3].

Existing methods for designing board-level functional testing strategies are broadly categorized into two types [4]: test ordering and test selection. The former adjusts the testing order of the testing items, thereby reducing the testing cost by terminating the testing process of faulty motherboards in advance [5]; the latter selects specific testing items from each motherboard for testing, thus reducing the overall testing cost for all motherboards. The latter often outperforms the former in testing high-yield products [6]. As product yield rates continue to improve, test selection is widely used for functional testing of various circuits [7–9].

However, existing test selection methods optimize testing strategies based solely on the conventional attributes of the

testing items, often ignoring the reliability information of the testing object. Since the board fabrication process often has frequent variations in working conditions, neglecting reliability information can easily lead to a significant deviation between the established optimization model and the actual process. The optimized testing strategy is prone to overfitting in practical applications, making it difficult to effectively reduce the testing cost [10].

Enhancing pure optimization modeling by incorporating reliability analysis is an effective approach to address the aforementioned issue. Existing optimization modeling methods based on reliability analysis typically utilize system reliability to establish the objective function or constraints of the optimization problem [11–13]. However, the reliability analysis methods in the existing studies have the following issues: Firstly, the current methods often lack the utilization of an effective reliability analysis model tailored to the research object, leading to challenges in ensuring the validity of qualitative reliability analysis and the accuracy of quantitative reliability calculations. Secondly, the reliability of the existing methods is often determined by a limited amount of data collected over a short timeframe, making it difficult to accurately reflect the reliability of the system and its components. These two issues result in a significant deviation between the calculated reliability and the actual value in practical applications of existing methods. This, in turn, impacts the effectiveness of optimization models based on reliability analysis.

To address the aforementioned issue, this article proposes an optimization modeling method that integrates statistical analysis and reliability analysis. By analyzing the reliability of the research object, the expression for the reliability of the key stage in the research object is formulated. Statistical

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analysis is used to exploit the inherent reliability information in massive process data, enabling the determination of the probability of the root causes of the object's failures based on the reliability information. On this basis, the reliability of the key stage is calculated according to the structure of the fault tree tailored for the research object. An optimization model is established based on the calculated reliability, and a board-level functional testing strategy with strong generalization ability to reduce testing costs is derived by solving the developed optimization model.

The main contents of the rest of this article are as follows: Section 2 provides a brief description of the functional testing process; Section 3 proposes an optimization modeling method that integrates statistical analysis and reliability analysis and introduces method evaluation indexes; Section 4 carries out simulation experiments to verify the effectiveness of the method; Section 5 provides a summary of the full article.

## 2 Background

To ensure that electronics, especially their motherboards, function properly, board-level and system-level functional testing stages are performed sequentially after the board fabrication process. Both stages assess several functional items serially.

The board-level functional testing stage usually determines the test status or test order of the functional items by developing a testing strategy. If all testing items of a motherboard pass the test, the motherboard is regarded as a qualified product. However, if one item fails the test, the motherboard is regarded as faulty and sent to a repair center. The repair center will conduct more detailed tests on the faulty motherboard, determine the underlying causes of the failure based on the testing outcomes and practical experience, repair the relevant components, and record it in the repair log.

Motherboards that pass the board-level functional testing will be assembled into a finished product. All components of the finished product will then be tested in the system-level functional testing stage. If all items of the product pass the test, the product will be considered qualified. If not, the product is sent to the repair center for disassembly, additional testing, and repair.

If a motherboard has untested faulty components, it is considered a false negative motherboard, meaning it is incorrectly classified as a functional one. The motherboard will then be assembled into a finished product. During the system-level functional testing stage, the finished product will be detected as faulty and sent for repair.

The testing outcomes are binary data, where '0' indicates that the motherboard or finished product failed the test on that item, and '1' indicates that it passed the test. Let  $n$  and  $m$  denote the number of motherboards and the number of tested items, respectively, the testing outcomes of the board-level functional testing stage can be represented as a data set  $D \in \{0, 1\}^{n \times m}$ . If there are untested functional items in the board-level functional testing stage, the values of the corresponding elements of  $D$  are not immediately available. However, since all functional testing items will be tested in the system-level functional testing stage to ensure product quality, the testing outcomes from the system-level functional testing stage can be used to determine the values of

all elements in the data set  $D$ .

The cost of functional testing mainly consists of the time cost of testing functional items and the cost of repairing faulty motherboards and final products. Except for the time cost of the system-level functional testing stage, the time cost, as well as the rework cost of the false negative motherboards and final products, are all determined by the board-level testing strategy. Therefore, designing an efficient board-level functional testing strategy is the key to reducing the overall cost of functional testing. In this article, we focus solely on the mainstream testing strategy design method: test selection. A test selection strategy represents the testing status of functional testing items, and it is typically denoted by a logic vector  $S \in \{0, 1\}^m$ .

## 3 Method

### 3.1 Reliability Analysis Integrating Statistical Analysis

The cost of reworking false negative motherboards accounts for a relatively high percentage of the overall cost of testing. The cost is essentially determined by the reliability of the board-level functional testing stage with respect to the system-level functional testing stage. Therefore, this paper starts with analyzing the reliability and designing an effective method to reduce the overall cost of testing.

When the test selection strategy is used, the board-level functional testing items can be categorized into two types according to the strategy: testing items and untested items. Since the testing items are tested in series, the testing items form a serial subsystem, while the untested items form another. Assuming that testing the faulty components of a faulty motherboard will certainly identify it as faulty, then the presence of a false negative motherboard is caused by the untested items. Therefore, for the system-level functional testing, the reliability of the subsystem consisting of testing items from the board-level functional testing stage is 100%, while the unreliability arises solely from the subsystem comprising untested items. Therefore, the reliability of the board-level functional testing stage with respect to the system-level functional testing stage can be calculated as follows:

$$R(S) = \prod_{j=1}^m R_j | (S_j = 0) \quad (1)$$

where  $R_j$  denotes the reliability of the motherboard component corresponding to the  $j$ th testing item.

To determine the reliability of a motherboard component, it is necessary to analyze the inherent causes of its failure. Fault tree analysis is an effective tool for analyzing the possible causes of failures of a system and its components and their probability of occurrence. In our previous work [14], we used this tool to build a fault tree tailored to the board-level functional testing stage of a laptop motherboard. In this fault tree, the top event is the motherboard failure, the first-level intermediate events are the failures of the motherboard components, the basic events are the underlying causes of the motherboard component failures, and the basic events are independent of each other. For the sake of brevity, the relevant diagrams and tables will not be repeated here; interested readers should refer to Ref [14].

In this article, we still take this laptop computer as an example to study the functional testing process and analyze the

reliability of its motherboard using the established fault tree. The reliability  $R(S)$  of the top event in Eq. (1) is calculated by integrating statistical analysis and utilizing the structure of the fault tree as follows:

First, a large number of historical testing outcomes of this motherboard are constructed as a dataset  $D^h \in \{0, 1\}^{n^h \times m}$ , where  $n^h$  denotes the number of motherboards that have undergone the board-level functional testing stage. Then, a repair log corresponding to  $D^h$  for the motherboard and its finished product is obtained from the repair center. This log includes diagnostic and repair information for the root causes of the faulty motherboard in both the board-level and system-level functional testing stages. Next, another dataset is constructed using the repair logs and denoted as  $D^r \in \{0, 1\}^{n^r \times q}$ , where  $q$  denotes the number of basic events. In this dataset,  $D^r_{s,k} = 1$  denotes that the  $s$ th motherboard is repaired due to the occurrence of the  $k$ th basic event.  $D^r$  is a sparse matrix, and typically each row of  $D^r$  has only one element equal to 1.  $D^r$  contains inherent reliability information about the testing process. Data analytic of  $D^r$  is conducted as follows using statistical analysis. Use the following formula to calculate the number of occurrences of the  $k$ th basic event:

$$n_k^r = \sum_{s=1}^{n^r} (D^r_{s,k} = 1), k = 1, \dots, q \quad (2)$$

Based on the definition of reliability, the probability of the  $k$ th bottom event is computed and used as an estimate of the reliability of that event as follows:

$$R(X_k) = \frac{n^h - n_k^r}{n^h}, k = 1, \dots, q \quad (3)$$

Next, based on the fault tree structure, the reliability of the components corresponding to the first-level intermediate events is calculated as follows:

$$R(M_j) = \prod_{X_k \in B_j} R(X_k), j = 1, \dots, m \quad (4)$$

Since all first-level intermediate events correspond to board-level functional testing items, the reliability of each testing item can be obtained as follows:

$$R_j = R(M_j), j = 1, \dots, m \quad (5)$$

Finally, the reliability of the top event is calculated using Eq. (1) and Eqs. (3–5).

### 3.2 Reliability Analysis-Based Optimization Modeling

Reliability is an essential reflection of the quality of the testing object. The reliability of the board-level functional testing stage with respect to the system-level functional testing stage depends on the reliability of the testing object and the test strategy, which remains constant regardless of the working conditions. Therefore, the test strategy derived from reliability analysis should possess strong generalization ability.

Decreasing the reliability of the board-level functional testing stage with respect to the system-level functional testing stage may lead to an increase in false negative motherboards and a decrease in testing time. Considering that the

increased rework cost due to an increase in the number of false negative motherboards tends to be higher than the cost savings from a decrease in testing time, maximizing the reliability of the board-level functional testing stage with respect to the system-level functional testing stage is a potentially effective strategy for reducing the overall cost of testing. Thus, the objective of the optimization problem in this section is expressed in the following form:

$$\max_{\mathcal{S}} R(S) \quad (6)$$

The testing time constraint is imposed on the optimization problem to avoid the accumulation of motherboards. To mitigate overfitting, the average testing time for each testing item is obtained from the historical testing time  $T^h \in \mathbb{R}^{n^h \times m}$  by the following equation:

$$\bar{t}_j^h = \frac{1}{n^h} \sum_{i=1}^{n^h} T_{i,j}^h, j = 1, \dots, m \quad (7)$$

where  $T_{i,j}^h$  denotes the time cost of testing the  $j$ th item on the  $i$ th historical motherboard.

Let  $t^0$  be the testing time threshold for each motherboard, which is determined by the motherboard fabrication schedule. The time constraint for the test can be expressed as:

$$\sum_{j=1}^m \bar{t}_j^h | (S_j = 1) \leq t^0 \quad (8)$$

Based on Eq. (6) and Eq. (8), a binary optimization problem is formulated as follows:

$$\max_{\mathcal{S}} R(S) \quad (9)$$

$$\text{s.t.} \sum_{j=1}^m \bar{t}_j^h | (S_j = 1) \leq t^0 \quad (10)$$

$$\mathcal{S} \in \{0, 1\}^m \quad (11)$$

The optimal testing strategy can be obtained by solving the optimization problem (9–11).

### 3.3 Evaluation Criteria

This subsection introduces three criteria for evaluating the performance of the selected testing strategy, namely false negative rate (FNR), average testing time cost, and average cost of testing.

FNR denotes the ratio of faulty motherboards not detected by the testing strategy  $\mathcal{S}$  to the total number of actual faulty motherboards. Based on Section 2, The detailed steps for calculating FNR are as follows:

The actual number of qualified motherboards can be obtained by logically analyzing the testing outcomes as follows:

$$n_N = \sum_{i=1}^n \left[ \left( \bigwedge_{j=1}^m (D_{i,j} = 1) \right) \equiv \top \right] \quad (12)$$

where  $\top$  denotes the logical truth.

The actual number of faulty motherboards can be obtained by subtracting the number of qualified motherboards from the total number of motherboards as follows:

$$n_P = n - n_N \quad (13)$$

By analyzing the logical relationship between the testing outcomes, the number of faulty motherboards detected using the testing strategy  $\mathcal{S}$  can be calculated as follows:

$$n_{TP}(\mathcal{S}) = \sum_{i=1}^n \left[ \left( \bigvee_{j=1}^m (D_{i,j} = 0) \mid (S_j = 1) \right) \equiv \top \right] \quad (14)$$

The number of false negative motherboards is calculated as follows using Eqs. (13–14):

$$n_{FN}(\mathcal{S}) = n_P - n_{TP}(\mathcal{S}) \quad (15)$$

Then the FNR, which reflects the quality of testing, can be calculated as follows:

$$\text{FNR}(\mathcal{S}) = \frac{n_{FN}(\mathcal{S})}{n_P} \quad (16)$$

The cost of repairing a false negative motherboard in the system-level functional testing stage is determined by  $n_{FN}(\mathcal{S})$  and the cost of repairing each motherboard in the finished product. The cost of rework depends on a variety of factors and varies for each motherboard. For simplicity, assuming that the repair cost is the same for each motherboard and converted to repair time, the rework cost of the process can then be simplified as a constant and denoted as  $c_{r,FN}$ . Similarly, the rework cost of a faulty motherboard detected by the board-level functional testing stage is determined by  $n_{TP}(\mathcal{S})$  and the rework cost per motherboard, assuming that the rework cost per motherboard for this stage is  $c_{r,TP}$ , which is usually significantly lower than  $c_{r,FN}$ . The exact values of both  $c_{r,FN}$  and  $c_{r,TP}$  are determined by practical experience.

The average testing time per motherboard is another important criterion for evaluating the effectiveness of the testing strategy. This cost reflects the speed of testing, which can be calculated as follows:

$$c_t(\mathcal{S}) = \frac{1}{n} \sum_{i=1}^n \sum_{j=1}^m T_{i,j} \mid (S_j = 1) \quad (17)$$

Assume that the total cost of functional testing is the sum of testing time cost and rework cost. Then the testing time cost and rework cost can be integrated into a comprehensive criterion based on the number of motherboards tested and repaired. This criterion is defined as the average cost of testing per motherboard and can be expressed as follows:

$$c(\mathcal{S}) = \frac{nc_t(\mathcal{S}) + c_{r,TP}n_{TP}(\mathcal{S}) + c_{r,FN}n_{FN}(\mathcal{S})}{n} \quad (18)$$

The testing strategy with the lowest  $c(\mathcal{S})$  value is the one that can effectively balance the quality and speed of testing.

## 4 Case Study

This section validates the effectiveness of the proposed method using the functional testing process of a laptop motherboard mentioned in Section 3.

### 4.1 Data Preparing

To protect the trade secrets of the electronics manufacturer, the following method is used to generate simulation data that is similar to the actual data:

The number of board-level functional testing items is set to 16, and the motherboard components tested are the same as those listed in Ref [14]. According to the actual value of the yield rate of each testing item, the yield rate of each testing item is set as a random number uniformly distributed on the interval [0.999, 1]. The number of motherboards  $n^h$  in the historical test log is set to  $2e7$  to capture enough repair logs. Historical functional testing outcomes are randomly generated based on the yield rates of testing items and form a matrix  $D^h \in \{0, 1\}^{2e7 \times 16}$ . From  $D^h$ , the number of faulty motherboards detected in the historical functional testing  $n^r$  is 135,048. The repair logs of the faulty motherboards form a matrix  $D^r \in \{0, 1\}^{135,048 \times 24}$ , where the elements of each column of the matrix are randomly generated based on the probability of occurrence of the corresponding basic event. Set the number of motherboards currently under test,  $n$ , to  $5e4$ . Generate the current functional testing outcomes randomly according to the yield rate and form a matrix  $D \in \{0, 1\}^{5e4 \times 16}$ .

According to the actual testing procedure, the mean testing time for each item  $\bar{t}_j$  is set as a random number uniformly distributed between 0.1 and 11 seconds, with the standard deviation of the testing time set as  $\bar{t}_j/100$ . Two datasets containing the testing time of the motherboard are generated based on the mean and standard deviation mentioned above. The first dataset corresponds to  $D^h$  and is denoted as  $T^h \in \mathbb{R}^{2e7 \times 16}$ ; the second dataset corresponds to  $D$  and is denoted as  $T \in \mathbb{R}^{5e4 \times 16}$ . Based on the current progress of the board fabrication process, the testing time threshold for each motherboard is set to 75 seconds. In addition, based on the actual repair cost, the repair costs  $c_{r,TP}$  and  $c_{r,FN}$  are set at 0.5 hours and 5 hours, respectively.

The first 60% of the dataset  $D$  is used as a training set for model training, while the remaining 40% is used as a test set to validate the effectiveness of the testing strategy. Table 1 presents the yield rates of the testing items on the training and test sets, denoted as  $y_{\text{train}}$  and  $y_{\text{test}}$ , respectively. This table also presents the percentage changes of the yield rates in the test set with respect to the training set, and bold values highlight significant yield variations in the corresponding testing items.

### 4.2 Ablation Study

To fully verify the effectiveness of the proposed method, two sets of ablation experiments are designed as follows:

- 1) Modify the way of obtaining reliability in the objective function (9): use the testing outcomes of the training set to calculate the yield rate of each testing item, as an approximation of the reliability of the corresponding component. Solve the modified optimization problem and denote the resulting optimal testing strategy as  $\mathcal{S}_{\text{approx}R}$ .
- 2) Modify the objective function (9) to minimize the average cost of testing on the training set  $c_{\text{train}}(\mathcal{S})$ . Solve the modified optimization problem and denote the resulting optimal testing strategy as  $\mathcal{S}_{\text{min}c}$ .

The first ablation experiment aims to verify the effectiveness of the strategy obtained when the reliability is inaccurately calculated using the reliability analysis model tailored to the research object. The second ablation experiment aims

Table 1: Values and Percentage Changes of Yield Rates on the Training and Test Sets

No. of testing item	$y_{train}$	$y_{test}$	Percentage change
1	0.99923	0.99860	<b>-0.0634%</b>
2	0.99957	0.99920	<b>-0.0367%</b>
3	0.99963	0.99925	<b>-0.0383%</b>
4	0.99993	1.00000	0.0067%
5	0.99943	0.99945	0.0017%
6	0.99980	0.99960	-0.0200%
7	0.99993	0.99990	-0.0033%
8	0.99957	0.99945	-0.0117%
9	1.00000	0.99930	<b>-0.0700%</b>
10	0.99943	0.99925	-0.0183%
11	0.99947	0.99890	<b>-0.0567%</b>
12	0.99953	0.99930	-0.0233%
13	0.99947	0.99925	-0.0217%
14	0.99980	1.00000	0.0200%
15	0.99943	0.99950	0.0067%
16	0.99943	0.99920	-0.0233%

to verify the effectiveness of the strategy obtained when the reliability information of the testing object is not effectively utilized. For simplicity, the methods corresponding to the two comparative experiments are referred to as the “reliability approximation method” and the “cost minimization method”, respectively. In addition, the strategy obtained by the proposed method is denoted as  $S_{ours}$ .

This simulation case study was carried out on a Windows 10 PC equipped with an Intel Core 2.5GHz CPU and 32GB of RAM using MATLAB R2023a. Monte Carlo simulation was used to solve each optimization problem. The number of simulation iterations for each round of optimization is set to 5,000. The running time of the proposed method and the methods in the ablation study are shown in Table 2.

Table 2: Running Time of Different Methods

Methods	Running time/sec
Proposed method	<b>0.0031</b>
Reliability approximation method	0.0034
Cost minimization method	6.8910

The testing strategies obtained from each method are shown in Table 3; the values of the evaluation criterion of each method, together with the percentage changes or changes of the methods in the ablation study with respect to the proposed method on the training and test sets are shown in Table 4 and Table 5, respectively.

### 4.3 Result Analysis

From Table 1, it can be seen that the working conditions of the test set have changed compared to the training set, resulting in relatively large variations in the yield rates of several testing items.

From Table 4 and Table 5, it can be seen that the evaluation criteria of strategy  $S_{ours}$  are similar to those of  $S_{approx R}$  in the training set. However, in the test set, the values of FNR and the average cost of testing for strategy  $S_{ours}$  are significantly better than those of strategy  $S_{approx R}$ . This suggests that the improvement of computational accuracy of the

reliability helps to obtain a more reliable testing strategy, which improves the generalization performance of the strategy when working conditions change. It can also be seen from Table 3 that the 9th item is not tested by  $S_{approx R}$ , but is tested by  $S_{ours}$ . According to the analysis presented in Section 3.1, the utilization of the strategy  $S_{approx R}$  leads to a decrease in the reliability of the board-level functional testing stage, resulting in a tendency for performance deterioration on the test set.

It can also be seen from Table 4 and Table 5 that the average cost of testing for the strategy  $S_{min c}$  is the lowest among the three strategies on the training set. This is because the goal of the cost minimization method is to minimize the average cost of testing on the training set. However, on the test set, the average cost of testing for this strategy is higher than that of the other two strategies. It can be seen that the cost minimization approach suffers from more significant overfitting when the working conditions change, as it does not utilize the inherent reliability information in the historical testing outcomes. It can also be seen from Table 3 that the number of functional items tested by  $S_{min c}$  is fewer than that of the other strategies. This leads to a significantly lower average testing time than that of the other strategies. However, it also results in a significantly higher value of the FNR criterion than the other strategies, resulting in a significantly greater number of false negative motherboards and causing higher rework costs and total cost of testing.

In addition, according to Table 2, the running time of the proposed method is the lowest among the three methods. It is close to that of the reliability approximation method. Since these two methods do not require frequent computation of cost function values, their running time is significantly lower than that of the cost minimization method. In practical applications, a lower running time helps in making timely adjustments to the testing strategy, thereby further reducing the testing cost.

Based on the above analysis, it can be seen that the proposed method, which integrates statistical analysis and reliability analysis, can select testing strategies with strong generalization ability, perform best on the test set, and acquire testing strategies with the highest efficiency. This approach has the potential to significantly reduce the cost of functional testing in practical applications.

## 5 Conclusion

This article proposes an optimization modeling method that integrates statistical analysis and reliability analysis. By analyzing the system’s reliability, the expression for the reliability of its key stage was formulated. Statistical analysis was utilized to exploit the inherent reliability information in the massive process data. The probability of system failures’ root causes was determined based on this reliability information. The reliability of the key stage was quantitatively calculated based on the structure of the tailored fault tree for the system. On this basis, the testing strategy was determined by establishing a binary optimization model. The proposed method has been verified to be capable of generating testing strategies with strong generalization ability and effectively reducing the cost of functional testing by over 10% using simulation data similar to the actual data.

Table 3: Board-Level Functional Testing Strategies Obtained by Different Methods

Testing strategy	Number of functional testing items																Total number of testing items
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
$S_{\text{ours}}$	1	0	1	0	1	1	0	1	1	1	1	1	1	1	1	1	13
$S_{\text{approx}R}$	1	0	1	0	1	1	0	1	0	1	1	1	1	1	1	1	12
$S_{\text{min}c}$	1	0	1	0	1	0	0	1	0	1	1	0	1	1	1	1	10

Table 4: Evaluation Criteria of Different Testing Strategies on the Training Set

Testing strategy	Average testing time/sec		FNR		Average cost of testing/sec	
	Value	Percentage change	Value	Change	Value	Percentage change
$S_{\text{ours}}$	74.9424	\	<b>8.47%</b>	\	94.9224	\
$S_{\text{approx}R}$	72.7853	-2.88%	<b>8.47%</b>	0.00%	92.7653	-2.27%
$S_{\text{min}c}$	<b>48.2619</b>	-35.60%	28.04%	19.58%	<b>88.2219</b>	-7.06%

Table 5: Evaluation Criteria of Different Testing Strategies on the Test Set

Testing strategy	Average testing time/sec		FNR		Average cost of testing/sec	
	Value	Percentage change	Value	Change	Value	Percentage change
$S_{\text{ours}}$	74.9406	\	<b>9.14%</b>	\	<b>107.2506</b>	\
$S_{\text{approx}R}$	72.7834	-2.88%	16.24%	7.11%	116.4334	8.56%
$S_{\text{min}c}$	<b>48.2603</b>	-35.60%	32.99%	23.86%	118.6403	10.62%

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